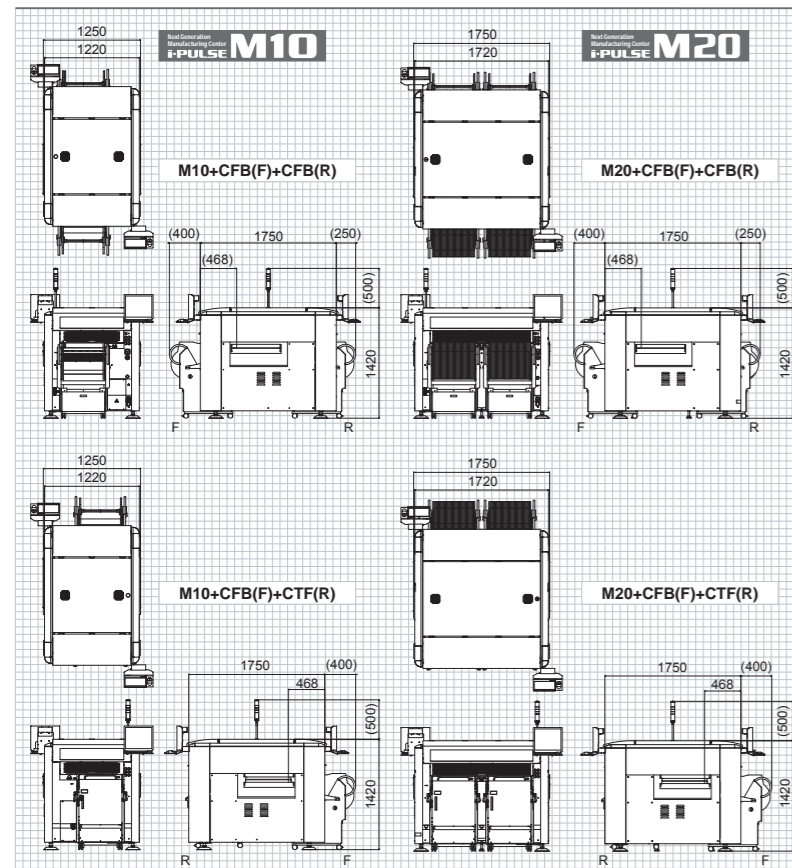


Specifications

Item	i-PULSE M10	i-PULSE M20
Board size (with buffer unused)	Min. L50 x W30mm to Max. L980 x W510mm *1	Min. L50 x W30mm to Max. L1,480 x W510mm *2
(with input or output buffer used)	Min. L50 x W30mm to Max. L420 x W510mm	—
(with input and output buffers used)	Min. L50 x W30mm to Max. L330 x W510mm	Min. L50 x W30mm to Max. L540 x W510mm
Board thickness	0.4 – 4.8mm	
Board flow direction	Left to right (Std)	
Board transfer speed	Max 900mm/sec	
Placement speed (4 heads + 1 theta) Opt. Cond.	0.15sec/CHIP (24,000CPH)	
(4 heads + 4 theta) Opt. Cond.	0.15sec/CHIP (24,000CPH)	
(6 heads + 2 theta) Opt. Cond.	0.12sec/CHIP (30,000CPH) *3	
(4 heads + 1 theta) IPC9850	19,000CPH	
(4 heads + 4 theta) IPC9850	19,000CPH	
(6 heads + 2 theta) IPC9850	23,000CPH *3	
Placement accuracy A ( $\mu+3\sigma$ )	CHIP +/- 0.040mm	
Placement accuracy B ( $\mu+3\sigma$ )	IC +/- 0.025mm	
Placement angle	+/-180 degrees	
Z axis control	AC servo motor	
Theta axis control	AC servo motor	
Component height	Max 30mm *4 (Pre-placed components: max 25mm)	
Applicable components	01005 – 120x90mm, BGA, CSP, connector, etc.	
Component package	8 - 56mm tape (F1/F2 Feeders), 8 - 88mm tape (F3 Electric Feeders), stick, tray	
Drawback check	Vacuum check and vision check	
Screen language	English, Chinese, Korean, Japanese	
Board positioning	Board grip unit, front reference, auto conveyor width adjustment	
Component types	Max 72 types (8mm tape), 36 lanes x 2	Max 144 types (8mm tape), 36 lanes x 4
Transfer height	900 +/- 20mm	
Machine dimensions, weight	L1250xD1750xH1420mm, Approx. 1,150kg	L1750xD1750xH1420mm, Approx. 1450kg
Power	3-phase 200/208/220/240/380/400/416/440V +/-10% (Transformer included), 50/60Hz	
Max consumption, capacity	1.1kW, 5.5kVA	1.1kW, 5.9kVA
Air pressure, consumption	0.45Mpa, 50(4 heads) or 75(6 heads) L/min A.N.R.	

\*1 : Max. 950mm for 6-head configuration \*2 : Max. 1,450mm for 6-head configuration \*3 : Common options to M20 and M10 \*4 : Board thickness + Component height = Max 30mm

External dimensions



Options

Item
4-axis 4-theta head
6-axis 2-theta head
Air pulse type dispense head
Screw pump type dispense head
Rear fixed multi-scan camera
Rear 36-lane fixed feeder bank
Rear side switches
Rear side operation system
UPS4
200mm conveyor extension, entrance/exit
Component setup verifier
Feeder relocatability
Waste tape box
Internal lighting
Lead coplanarity sensor
Safety cover, front/rear
Clamp unit for CFB/CTF
CFB-36E F3 Electric Feeder Bank Changer
CFB-36 F1/F2 Feeder Bank Changer
CTF-36C Cassette type Changeable Tray Feeder
FTF-36C Cassette type Fixed Tray Feeder
RTS-1 Removable Tray Station
Parts feeders
Offline software
iQ vision

Next Generation  
Manufacturing Center  
**i-PULSE M10/M20**





**M10**  
Max. board size **980 x 510mm**  
Applicable components **01005 to 120 x 90mm**  
Feeder capacity **72 lanes (8mm tape conversion)**  
Machine width **1,250mm**

**M20**  
Max. board size **1,480 x 510mm**  
Applicable components **01005 to 120 x 90mm**  
Feeder capacity **144 lanes (8mm tape conversion)**  
Machine width **1,750mm**

Revolutionary and unique new features included as standard ensure the M10 and M20 evolves into the ultimate super-flexible multi-purpose machine.

## Wide ranging component handling capability and high feeder capacity

### New super high speed multi-scan camera.



- Handling a full range of components from 01005 to 120 x 90mm as standard. (No optional camera needed)
- Image capture of chips can be performed with max. speed of 3,000mm/sec. High speed image capture and recognition are realized in accordance with component size.
- Introducing "D-SCAN" - New image capture system from i-PULSE.

### Max. feeder capacity 144 lanes on M20 with rear feeder banks (option).



### 3 types of head variations Max. component height 30mm as standard (board thickness + component height)



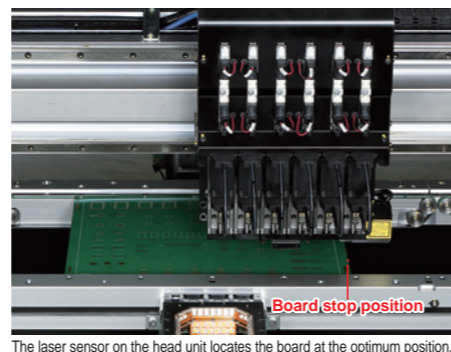
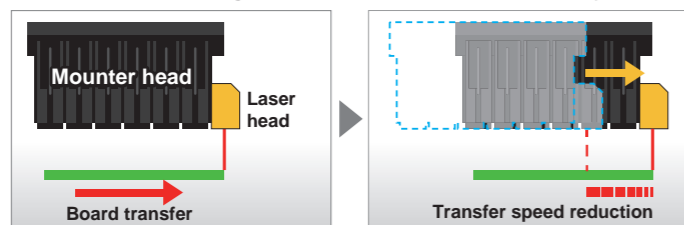
4-axis 1-theta head (Standard)

4-axis 4-theta head (High precision)

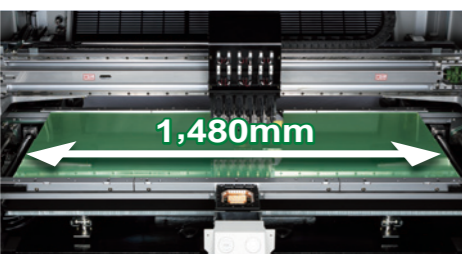
6-axis 2-theta head (High performance)

## New Multi-Conveyor System providing the highest large board handling capability on the market

With no mechanical board stoppers, utilizing a laser sensor to measure the board length, thus providing optimum board position for efficient component placement, regardless of size or shape. The Multi-Conveyor System can quickly and flexibly adapt to production changes with minimum operator activity.



Max. 1,480 x 510mm board can be handled as standard (M20).



M10 board size		M20 board size	
With buffer unused		With buffer unused	
Min. L50 x W30 to Max. L980 x W510mm		Min. L50 x W30 to Max. L1,480 x W510mm	
With input or output buffer used			
Min. L50 x W30 to Max. L420 x W510mm			
With input and output buffers used		With input and output buffers used	
Min. L50 x W30 to Max. L330 x W510mm		Min. L50 x W30 to Max. L540 x W510mm	

## In pursuit of ultimate flexibility and fast & easy setup

### New CFB-36E for use with F3 Electric Feeder.

The CFB-36E F3 Feeder Bank Changer, the CFB-36 F1/F2 Feeder Bank Changer and the CTF-36C Changeable Tray Feeder can be exchanged with each other. The CFB-36E and the CFB-36 can also be fitted to the same machine.



\* Fitted to M20 on the above pictures.

### New CTF-36C Changeable Tray Feeder.

Utilizing multi-magazine tray handling with intelligent function ensures high-speed production changeover.



## In pursuit of high accuracy placement

Gripper nozzles newly added in P type nozzles of light-weight and low-impact. Odd-form handling capability further increased.

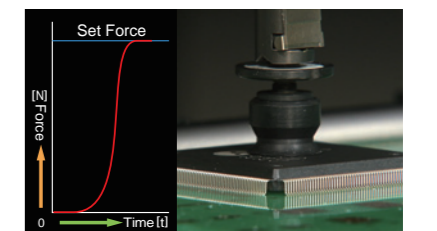


### Component coplanarity sensor (Option).

Floating leads are inspected and defective components are detected prior to placement.

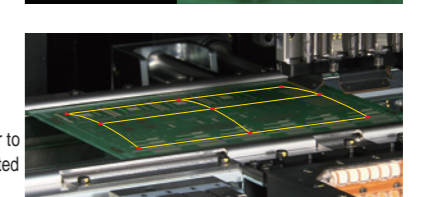


Placement force is fully controlled in real time to reduce stress to components.



### Placement height measuring laser unit as standard.

Board warp is measured with laser to ensure placement height is corrected before components are mounted.



## 3D hybrid placement functions

Dispense heads that can be exchanged with mount heads are newly developed. It becomes possible to make 3D placement where solder paste dispensing and component mounting can be alternately performed. Hybrid placement is now realized. The removable Dot Station can be fitted to the feeder bank.

